Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2996

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance :  $R_{DS}$  (ON) = 0.74  $\Omega$  (typ.)

• High forward transfer admittance :  $|Y_{fs}| = 6.8 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = 100 \mu A \text{ (max)} \text{ (VDS} = 600 \text{ V)}$ 

• Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	600	V	
Gate-source voltage		V <sub>GSS</sub>	±30	٧	
Drain current	DC (Note 1)	I <sub>D</sub>	10	Α	
	Pulse (Note 1)	I <sub>DP</sub>	30	A 	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	45	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	252	mJ	
Avalanche current		I <sub>AR</sub>	10	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 4.41 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 10 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



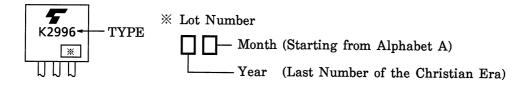
# **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V <sub>(BR)</sub> GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A	_	0.74	1.0	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5 A	3.4	6.8	_	S
Input capacitano	ce	C <sub>iss</sub>		_	1500	_	
Reverse transfe	e transfer capacitance $C_{rss}$ $V_{DS}$ = 20 V, $V_{GS}$ = 0 V, f = 1 MHz		_	13	_	pF	
Output capacitance		C <sub>oss</sub>	1	_	140	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\text{0 V}} \stackrel{\text{I}_{D} = 5 \text{ A}}{\text{0 V}} \stackrel{\text{OUT}}{\text{OUT}}$ $R_{L} = 60 \Omega$ $V_{DD} = 300 \text{ V}$	_	15	_	
	Turn-on time	t <sub>on</sub>		_	55	_	no
	Fall time	t <sub>f</sub>		_	27	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_W = 10 \mu s$	_	145	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	38	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		21	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$			17	_	

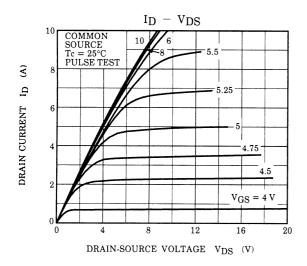
# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

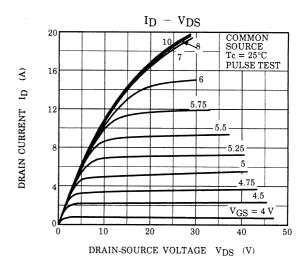
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	-	_	10	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	30	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V dI <sub>DR</sub> / dt = 100 A / μs		1600		ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 A / μs		17	-	μC

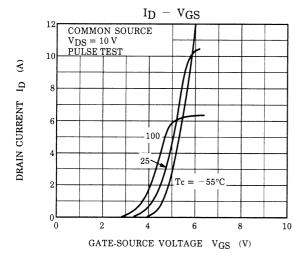
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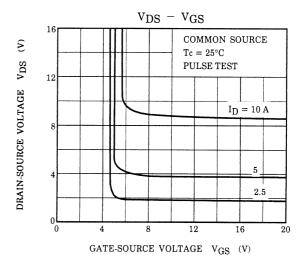


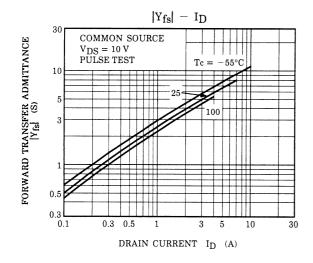
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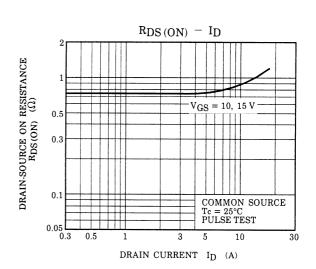




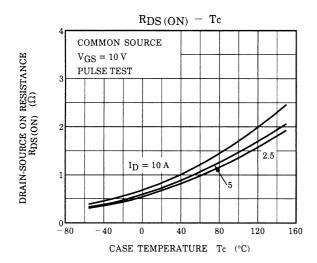


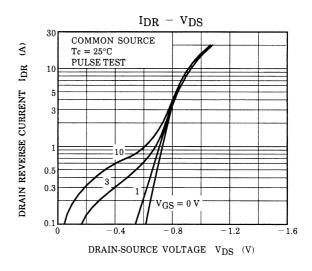


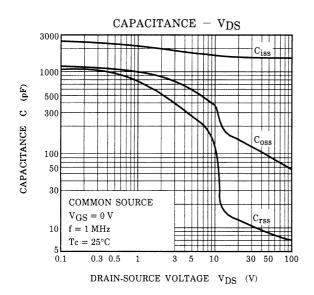


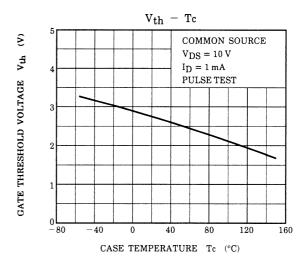


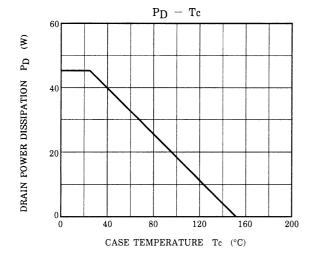
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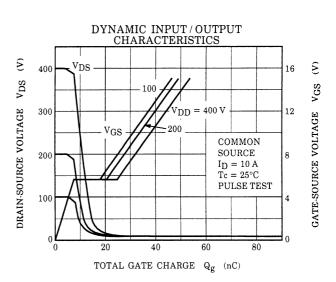




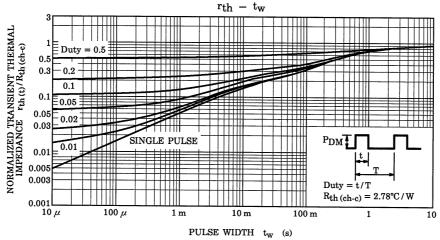




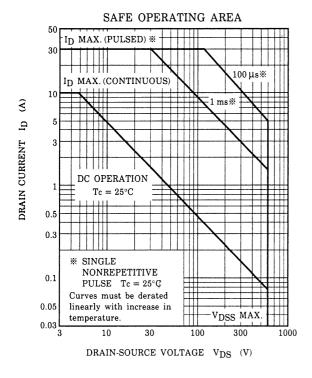


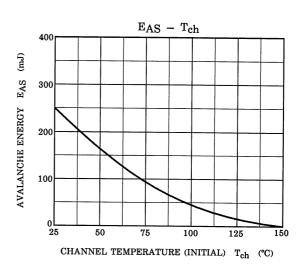


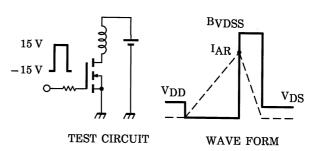
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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 4.41~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}\right)$$

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